☐ MN101CA2 Series

Туре	MN101CA27	MN101CFA2D		
Internal ROM type	Mask ROM	FLASH		
ROM (byte)	16K	64K		
RAM (byte)	0.5K	2K		
Package (Lead-free)	LQFP064-P-1414			
Minimum Instruction Execution Time	0.25 µs (at 2.7 V to 3.6 V, 8 MHz) 0.50 µs (at 1.8 V to 3.6 V, 4 MHz) 62.5 µs (at 1.8 V to 3.6 V, 32 kHz)			

■ Interrupts

RESET. Watchdog. External 2. External 6. Timer 0. Timer 1. Timer 6. Time base

■ Timer Counter

8-bit timer \times 2

Timer 0Square-wave/8-bit PWM output. Simple pulse width measurement

Timer 1Square-wave output

Timer 0, 1 can be cascade-connected

Time base timer: One-minute count setting

Watchdog timer × 1

Remote control carrier output

■ I/O Pins

I/O 16: Common use. Specified pull-up resistor available. Input/output selectable (bit unit)

Input 9: Common use. Specified pull-up resistor available

■ Display control function

LCD: 32 segments \times 4 commons (1/3 or 1/4 duty)

■ Special Ports

Buzzer output. Remote control carrier output. High-current drive port

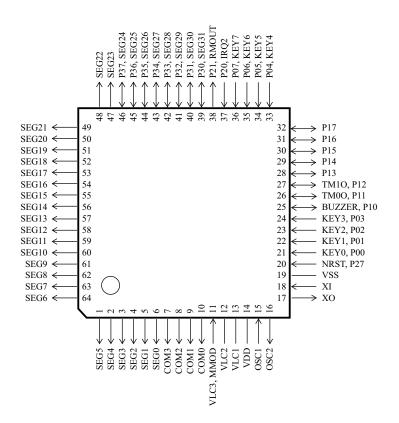
■ Electrical Charactreistics (Supply current)

Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	Uill
Operating supply current	IDD1	fosc = 8 MHz. VDD = 3 V		1.0	1.8	mA
	IDD2	fx = 32 kHz. VDD = 3 V		4.8	17	μA
Supply current at HALT	IDD3	$fx = 32 \text{ kHz. VDD} = 3 \text{ V. Ta} = 25 ^{\circ}\text{C}$		2.7	5	μA
	IDD4	$fx = 32 \text{ kHz. VDD} = 3 \text{ V. Ta} = 70 ^{\circ}\text{C}$			13	μA
Supply current at STOP	IDD5	VDD = 3 V. Ta = 25 °C			2	μA
		VDD = 3 V. Ta = 70 °C			8	μA

Note) Limit: Mask ROM version

Panasonic MAD00070DEM

■ Pin Assignment LQFP064-P-1414



MAD00070DEM Panasonic

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